



Manufacturer:
Epoxy Technology

Product Name:
EPO-TEK® OE138 Thixotropic High Temperature Epoxy, Heat Cure - Pre-Mixed and Frozen (3cc Syringe)

Manufacturer Part Number:
ETOE138-3CC

▶ [Click here for more details on the EPO-TEK® OE138 Thixotropic High Temperature Epoxy, Heat Cure - Pre-Mixed and Frozen \(3cc Syringe\)](#)



EPO-TEK® OE138
Technical Data Sheet
For Reference Only
High Temperature Thixotropic Epoxy

Date: October 2022
Rev: VII
No. of Components: Two
Mix Ratio by Weight: 10 : 1
Specific Gravity: Part A: 1.06 Part B: 1.02
Pot Life: 2 Hours
Shelf Life- Bulk: One year at room temperature
Shelf Life- Syringe: Six months at -40°C

Recommended Cure: 150°C / 1 Hour

Minimum Alternative Cure(s):
May not achieve performance properties below
150°C / 2 Minutes
80°C / 30 Minutes

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters.
- **TOTAL MASS SHOULD NOT EXCEED 50 GRAMS**

Product Description: EPO-TEK® OE138 is a two component epoxy with intermediate viscosity range between EPO-TEK®353ND and EPO-TEK® 353ND-T. It is designed for semiconductor glob top applications, as well as use in medical and fiber optic industries.

Typical Properties: Cure condition: 150°C / 1 Hour Different batches, conditions & applications yield differing results.
Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:			
* Color (before cure):	Part A: Tan	Part B: Amber	
* Consistency:	Smooth, pourable paste		
* Viscosity (23°C) @ 20 rpm:	4,000 - 7,000	cPs	
Thixotropic Index:	1.3		
* Glass Transition Temp:	≥ 90	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)	
Coefficient of Thermal Expansion (CTE):			
Below Tg:	21	x 10 ⁻⁶ in/in°C	
Above Tg:	128	x 10 ⁻⁶ in/in°C	
Shore D Hardness:	85		
Lap Shear @ 23°C:	> 2,000	psi	
Die Shear @ 23°C:	≥ 20	Kg	7,112 psi
Degradation Temp:	406	°C	
Weight Loss:			
@ 200°C:	0.18	%	
@ 250°C:	0.60	%	
@ 300°C:	1.40	%	
Suggested Operating Temperature:	< 300	°C (Intermittent)	
Storage Modulus:	392,573	psi	
Ion Content	Cl ⁻ : 334 ppm	Na ⁺ : 494 ppm	
	NH ₄ ⁺ : 4 ppm	K ⁺ : ND	
* Particle Size:	< 20	microns	
ELECTRICAL AND THERMAL PROPERTIES:			
Thermal Conductivity:	N/A		
Volume Resistivity @ 23°C:	≥ 9 x 10 ¹²	Ohm-cm	
Dielectric Constant (1KHz):	3.18		
Dissipation Factor (1KHz):	0.003		

Epoxy and Adhesives for Demanding Applications™

This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.

Contact the professionals at Fiber Optic Center for a quote or to get more details.

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Product specifications and data are subject to change without notice. FOC last update 2/3/2026.



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EPO-TEK® OE138 Advantages & Suggested Application Notes:

- Suitable for circuit assembly applications such as stacking SMDs, bonding ferrites cores, bonding inductor coils and power devices
- Used in chip on Board Globtops for encapsulation and environmental protection
- High temperature adhesive for hybrids and down hole sensors which can resist up to 300 C for extended periods of time
- Can be applied by screen printing, spatula, automatic dispenser or by hand
- Recommended for bonding metals, glass, ceramic, and many types of plastic
- OE138 changes to a dark amber color when properly cured for easy visual inspection

Epoxy Technology, Inc. Epoxies and Adhesives for Demanding Applications™

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